

Technical Data
Data Sheet N1582, Rev. -

150mA, Low Noise, Low Dropout Linear Regulator

Description:

The SULR1730 is a low noise, low dropout linear regulator, and is housed in a small SOT-23-5 package. The device is in the “ON” state when the SHDN pin is set to logic high level. A low dropout voltage of 90mV at 50mA load current is performed. It offers high precision output voltage of $\pm 2\%$. The quality of low quiescent current and low dropout voltage makes this device ideal for battery power applications. The internal reverse bias protection eliminates the requirement for a reverse voltage protection diode. The high ripple rejection and low noise provide enhanced performance for critical applications. The noise bypass pin can be connected an external capacitor to reduce the output noise level.

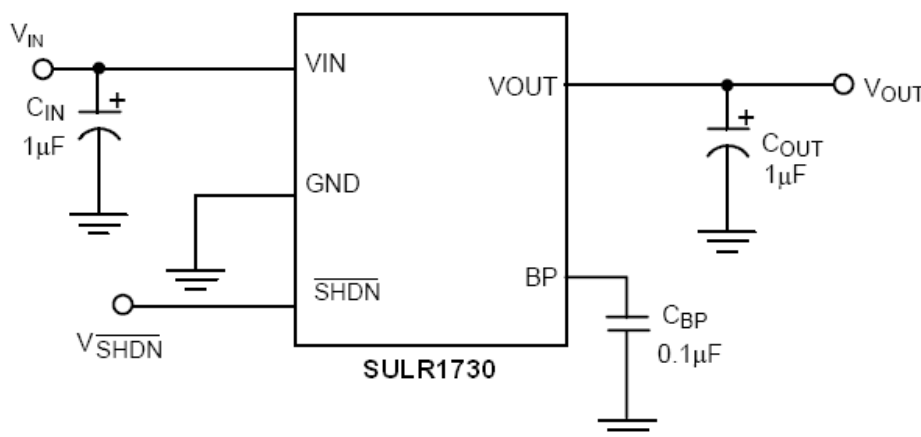
Features:

- Very Low Quiescent Current, 55 μ A
- Very Low Dropout Voltage, 90mV @ 50mA.
- Short Circuit and Thermal Protection.
- Available in $\pm 2\%$ Output Tolerance.
- 1.8V to 3.3V Output Voltage with 0.1V Increment.
- Active Low Shutdown Control.
- Low Noise.
- Low Profile Package: SOT-23-5

Applications:

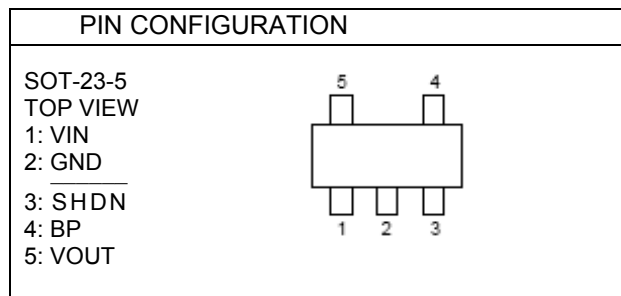
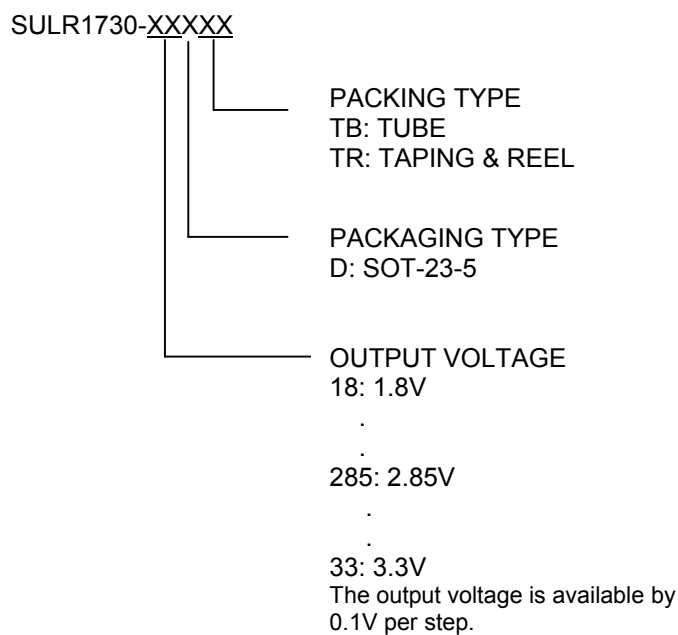
- Cellular Telephones.
- Pagers.
- Personal Communication Equipment.
- Cordless Telephones.
- Portable Instrumentation.
- Portable Consumer Equipment.
- Radio Control Systems.
- Low Voltage Systems.
- Battery Powered Systems.

Typical application circuit:



Low Noise Low Dropout Linear Regulator

Ordering Information:



Marking Diagram:

Part No.	Marking
SULR1730-18DTR	EC18G
SULR1730-33DTR	EC33G
SULR1730-285DTR	EC2JG



Absolute Maximum Ratings:

Supply Voltage	12V
Shutdown Terminal Voltage.....	12V
Noise Bypass Terminal Voltage	5V
Operating Temperature Range	-40°C to 85°C
Maximum Junction Temperature	125°C
Storage Temperature Range	-65°C ~ 150°C
Lead Temperature (Soldering) 10 sec.	260°C
Thermal Resistance Junction to Case SOT-23-5	130°C/W
Thermal Resistance Junction to Ambient SOT-23-5.....	220°C/W

(Assume no ambient airflow, no heatsink)

Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Test Circuit

Refer to TYPICAL APPLICATION CIRCUIT

Electrical Characteristics($C_{IN} = 1\mu F$, $C_{OUT} = 10\mu F$, $T_J=25^\circ C$, unless otherwise specified)(Note 1)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Quiescent Current	$I_{OUT} = 0mA$, $V_{IN} = 3.6\sim 12V$	I_Q		55	80	μA	
Standby Current	$V_{IN} = 3.6\sim 8V$, output OFF	I_{STBY}			0.1	μA	
GND Pin Current	$I_{OUT} = 0.1\sim 150mA$	I_{GND}		55	80	μA	
Continuous Output Current	$V_{IN} = V_{OUT} + 1V$	I_{OUT}			150	mA	
Output Current Limit	$V_{IN} = V_{OUT} + 1V$, $V_{OUT} = 0V$	I_{IL}	150	220		mA	
Output Voltage Tolerance	$V_{IN} = V_{OUT} + 1V$, no load	V_{OUT}	-2		2	%	
Temperature Coefficient		TC		50	150	ppm/ $^\circ C$	
Line Regulation	$V_{IN} = V_{OUT(TYP)} + 1V$ to $V_{OUT(TYP)} + 6V$	ΔV_{LIR}		2	7	mV	
Load Regulation	$V_{IN} = 5V$, $I_{OUT} = 0.1\sim 150mA$	ΔV_{LOR}		7	25	mV	
Dropout Voltage (1)	$I_{OUT} = 50 mA$	$V_{OUT} \geq 2.5V$	V_{DROP1}		90	160	mV
	$I_{OUT} = 100 mA$				140	230	mV
	$I_{OUT} = 150 mA$				200	350	mV
Dropout Voltage (2)	$I_{OUT} = 150 mA$	$V_{OUT} < 2.5V$	V_{DROP2}		700	mV	
Noise Bypass Terminal Voltage		V_{REF}		1.23		V	
Output Noise	$C_{BP} = 0.1\mu F$, $f = 1KHz$ $V_{IN} = 5V$	Δn		0.46		$\frac{\mu V}{\sqrt{Hz}}$	
SHUTDOWN TERMINAL SPECIFICATIONS							
Shutdown Pin Current		I_{SHDN}			0.1	μA	
Shutdown Pin Voltage (ON)	Output ON	$V_{SHDN(ON)}$	1.6			V	
Shutdown Pin Voltage (OFF)	Output OFF	$V_{SHDN(OFF)}$			0.6	V	
Shutdown Exit Delay Time	$C_{BP} = 0.1\mu F$, $C_{OUT} = 1\mu F$, $I_{OUT} = 30mA$	Δt		300		μS	
THERMAL PROTECTION							
Thermal Shutdown Temperature		T_{SD}		155		$^\circ C$	
Thermal Shutdown Hysteresis	Guaranteed by design	T_{HYST}		20		$^\circ C$	

Note 1: Specifications are production tested at $T_A=25^\circ C$. Specifications over the $-40^\circ C$ to $85^\circ C$ operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).

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Typical Performance Characteristics

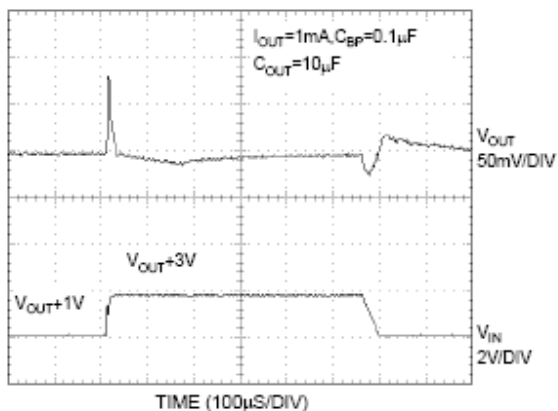


Fig. 1 Line Transient Response

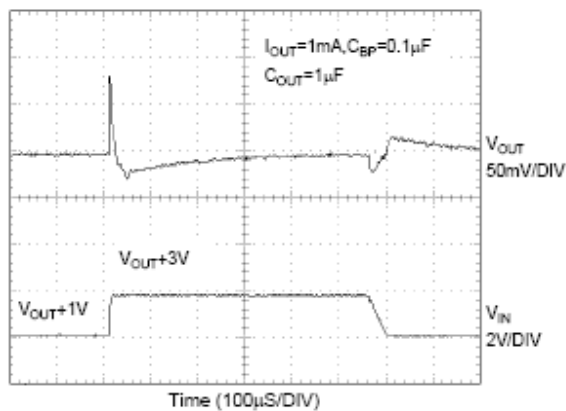


Fig. 2 Line Transient Response

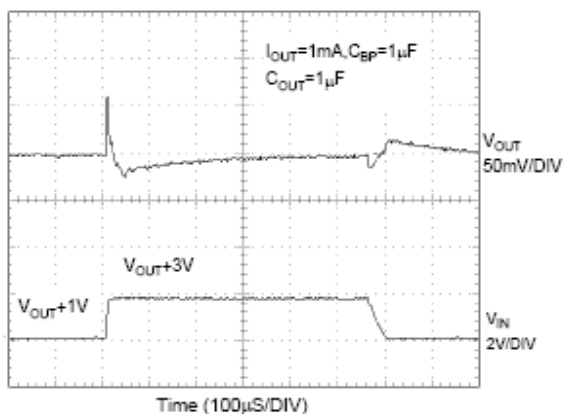


Fig. 3 Line Transient Response

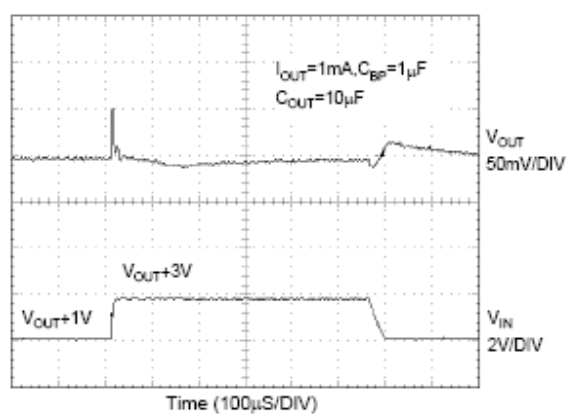


Fig. 4 Line Transient Response

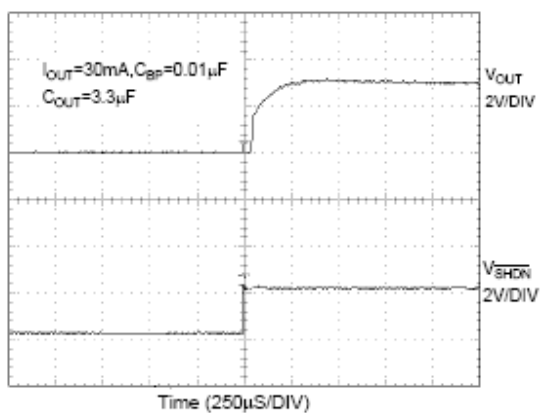


Fig. 5 Shutdown Exit Delay

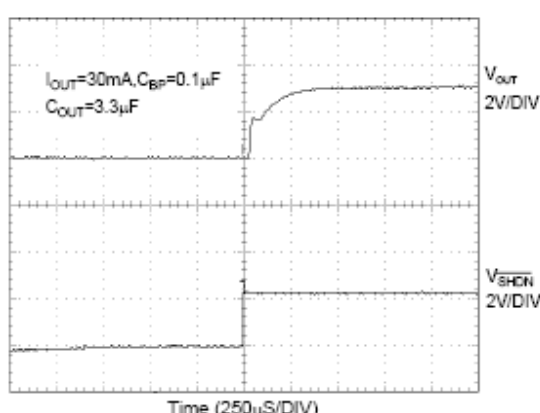


Fig. 6 Shutdown Exit Delay

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 Typical Performance Characteristics (Continued)

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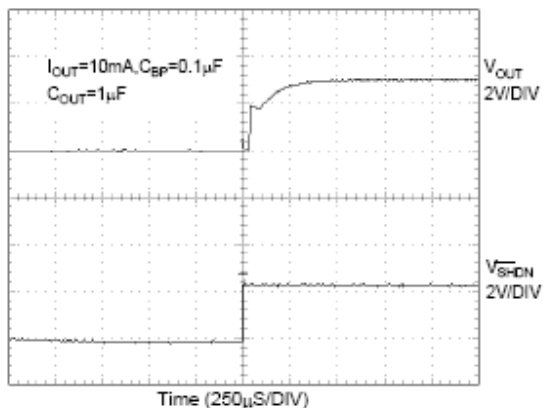


Fig. 7 Shutdown Exit Delay

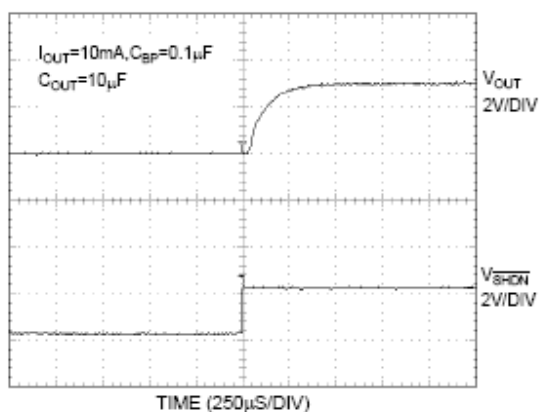


Fig. 8 Shutdown Exit Delay

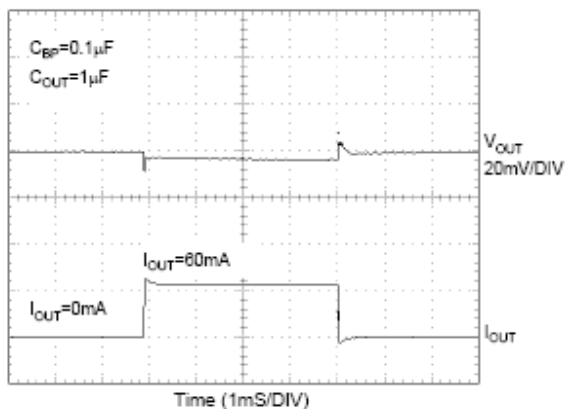


Fig. 9 Load Transient Response

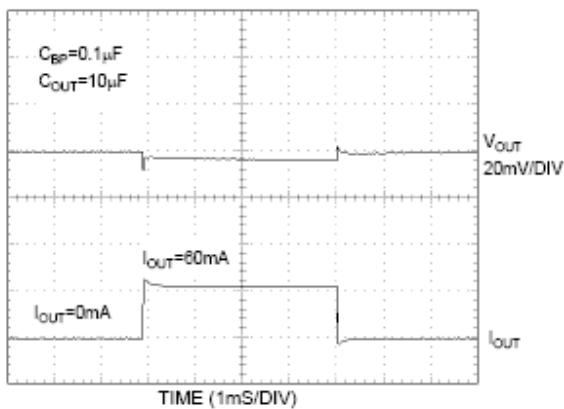


Fig. 10 Load Transient Response

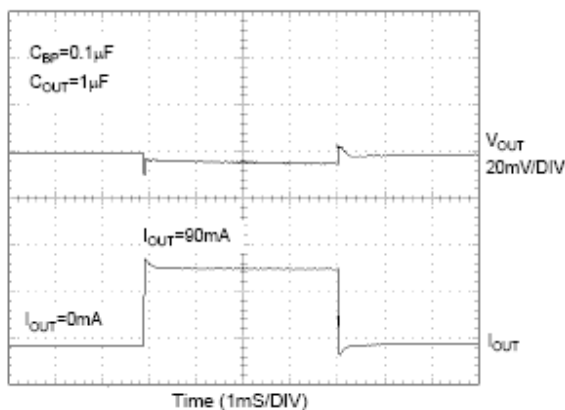


Fig. 11 Load Transient Response

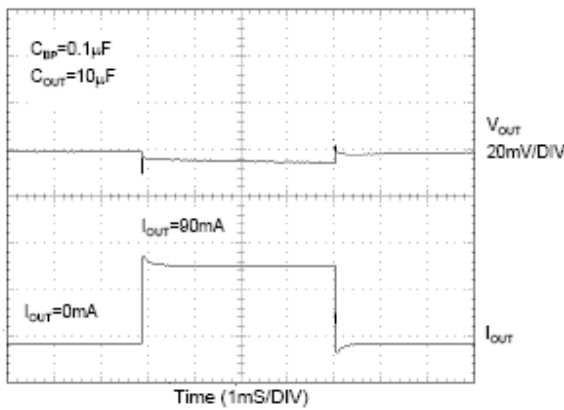


Fig. 12 Load Transient Response

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 Typical Performance Characteristics (Continued)

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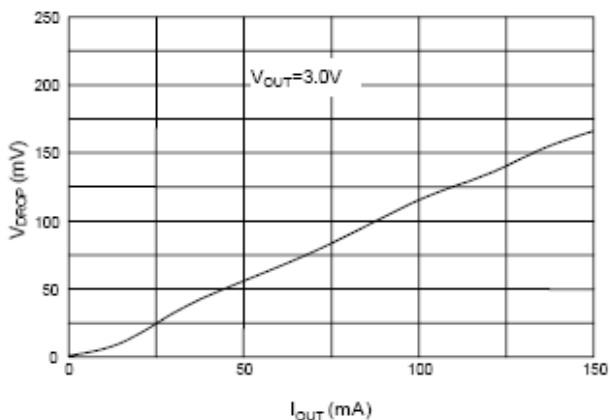


Fig. 13 Dropout Voltage vs. Output Current

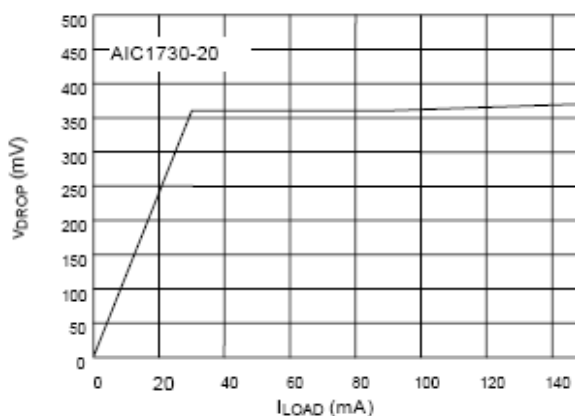


Fig. 14 Dropout Voltage vs. Output Current

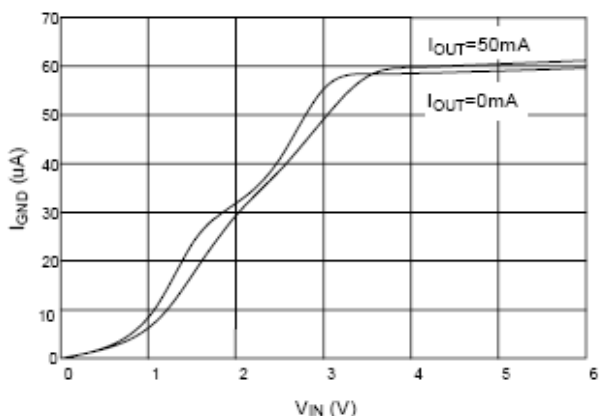


Fig. 15 Ground Current vs. Input Voltage (Vout=3.0V)

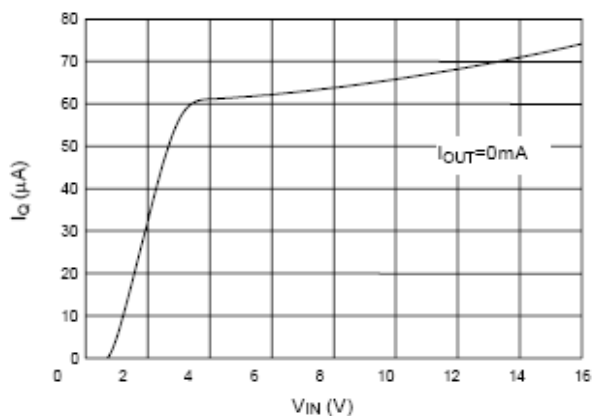


Fig. 16 Quiescent Current (ON Mode) vs. Input Voltage

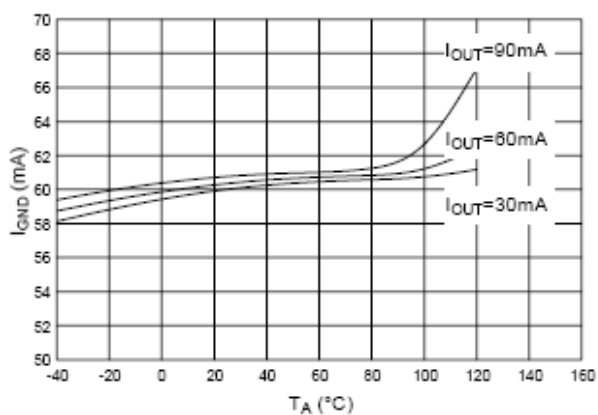


Fig. 17 Ground Current vs. Temperature

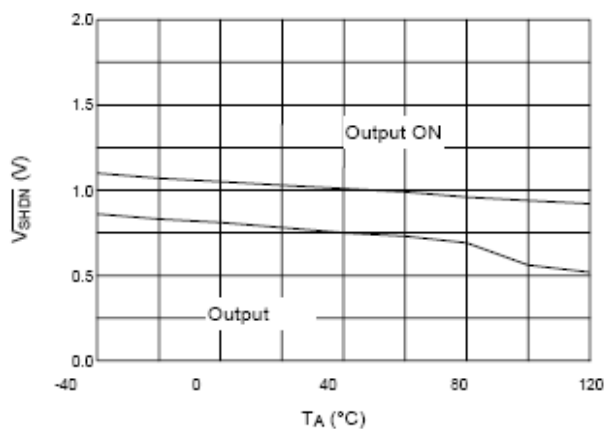


Fig. 18 Shutdown Voltage vs. Temperature

Typical Performance Characteristics (Continued)

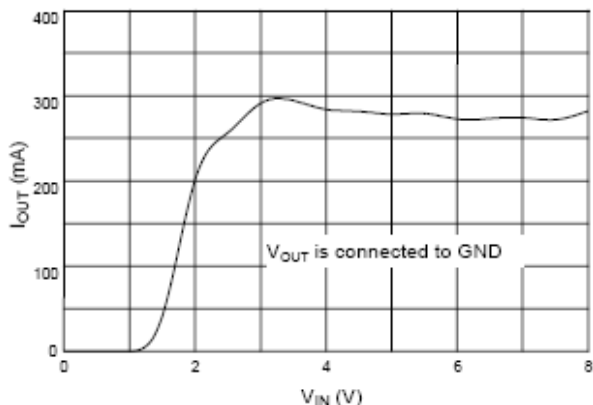


Fig. 19 Short Circuit Current vs. Input Voltage

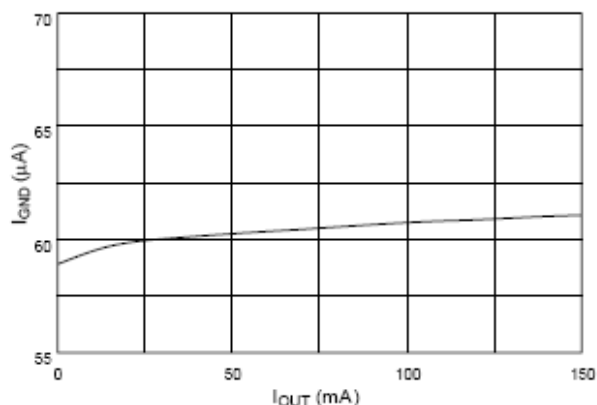


Fig. 20 Ground Current vs. Output Current

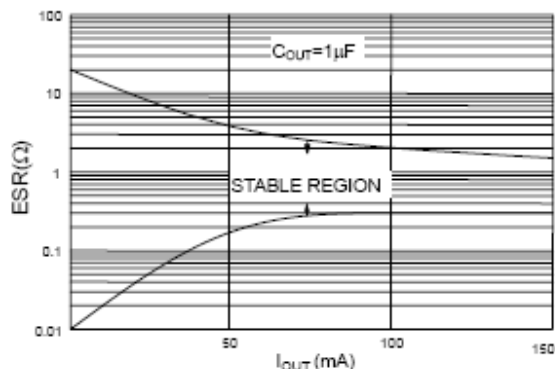


Fig. 21 Max Power Dissipation, $C_{OUT}=1\mu F$

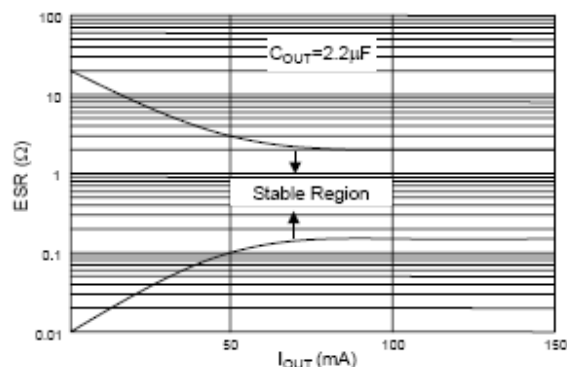


Fig. 22 Max Power Dissipation, $C_{OUT}=2.2\mu F$

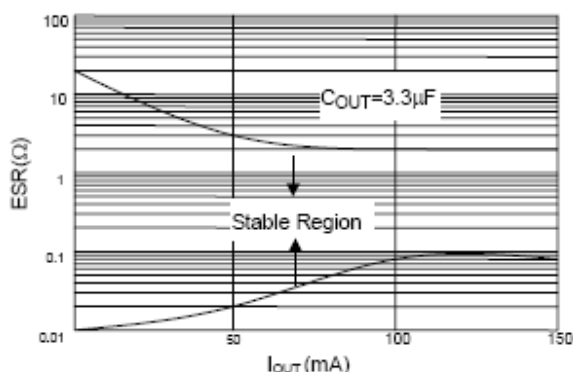


Fig. 23 Max Power Dissipation, $C_{OUT}=3.3\mu F$

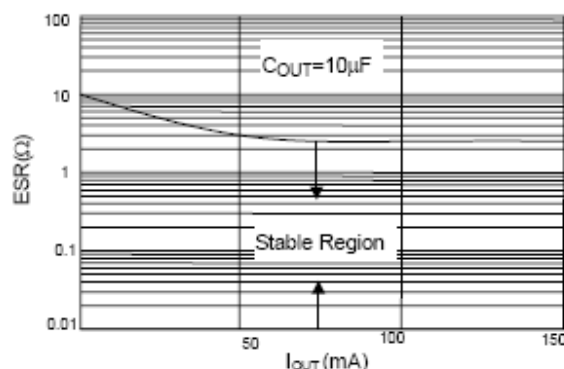
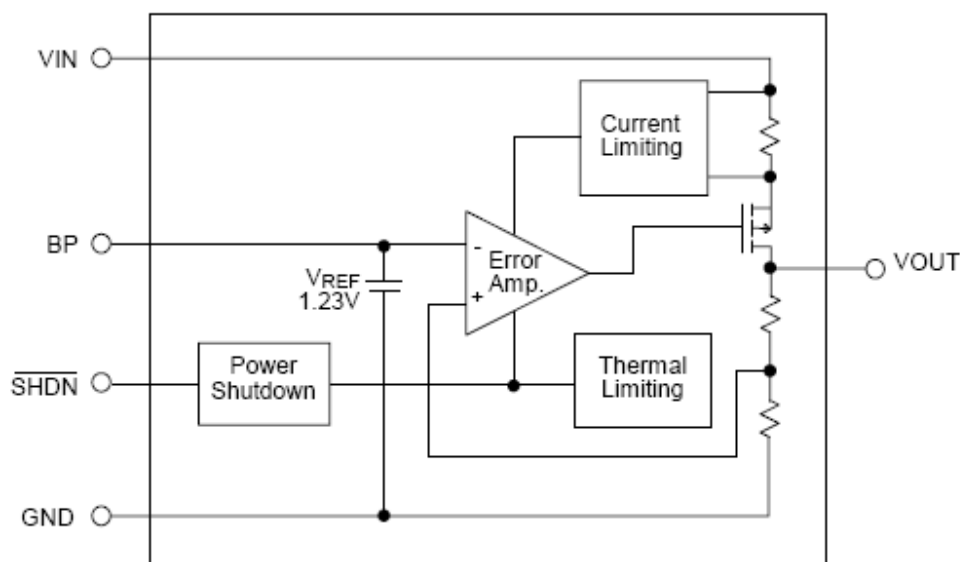


Fig. 24 Max Power Dissipation, $C_{OUT}=10\mu F$

Block Diagram



Pin Descriptions

- PIN 1 : VIN - Power supply input pin. Bypass with a 1 μ F capacitor to GND
- PIN 2 : GND - Ground pin.
- PIN 3 : SHDN - Active-Low shutdown input pin.
- PIN 4 : BP - Noise bypass pin. An external bypass capacitor connecting to BP pin to reduce noises at the output.
- PIN 5 : VOUT - Output pin. Sources up to 150mA.



Application Information

INPUT-OUTPUT CAPACITORS

Linear regulators require input and output capacitors to maintain stability. Input capacitor at 1 μ F with 1 μ F aluminum electrolytic output capacitor is recommended. And it should be selected within the Equivalent Series Resistance (ESR) range as shown in the figure 21, 22, 23, and 24. ESR of ceramic capacitor is lower and its electrical characteristics (capacitance and ESR) vary widely over temperature. In general, tantalum or electric output capacitor is suggested for heavy load.

Normally, the output capacitor should be 1 μ F (aluminum electrolytic) at least and rates for operating temperature range. Note that it's important to check selected manufactures electrical characteristics (capacitance and ESR) over temperature.

NOISE BYPASS CAPACITOR

0.1 μ F bypass capacitor at BP pin reduces output voltage noise. And the BP pin has to connect a capacitor to GND.

POWER DISSIPATION

The maximum power dissipation of SULR1730 depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

The power dissipation across the device is $P = I_{OUT} (V_{IN} - V_{OUT})$.

The maximum power dissipation is:

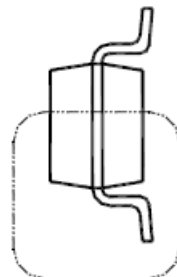
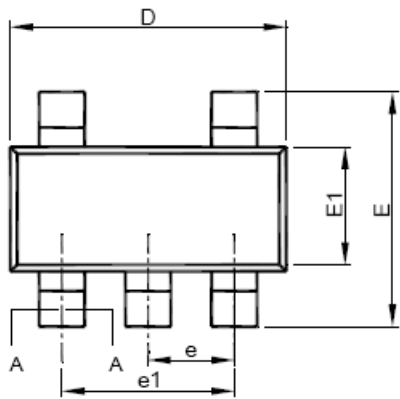
$$P_{MAX} = \frac{(T_J - T_A)}{(R_{\theta JB} + R_{\theta BA})}$$

Where $T_J - T_A$ is the temperature difference between the die junction and the surrounding air, $R_{\theta JB}$ is the thermal resistance of the package, and $R_{\theta BA}$ is the thermal resistance through the PCB, copper traces, and other materials to the surrounding air.

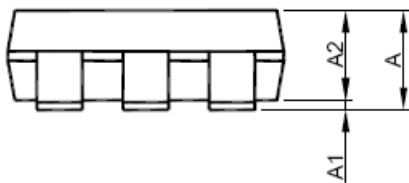
As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature. GND pin performs a dual function of providing an electrical connection to ground and channeling heat away. Therefore, connecting the GND pin to ground with a large pad or ground plane would increase the power dissipation and reduce the device temperature.

Physical Dimensions

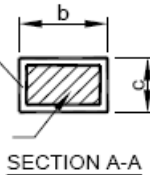
SOT-23-5 (unit: mm)



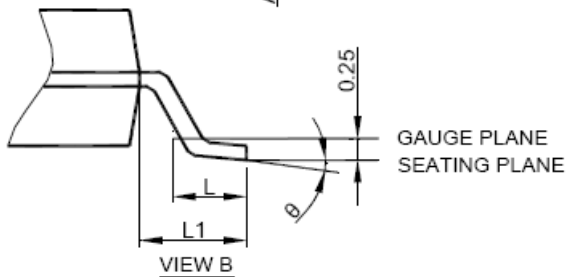
SEE VIEW B



WITH PLATING
BASE METAL



SECTION A-A



VIEW B

SYMBOL	SOT-23-5	
	MILLIMETERS	
	MIN.	MAX.
A	0.95	1.45
A1	0.05	0.15
A2	0.90	1.30
b	0.30	0.50
c	0.08	0.22
D	2.80	3.00
E	2.60	3.00
E1	1.50	1.70
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60
L1	0.60 REF	
q	0°	8°

Note: 1. Refer to JEDEC MO-178AA.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.

3. Dimension "E1" does not include inter-lead flash or protrusions.

4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



SULR1730

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